

2-PART SILICONE GAP FILLER TDG-T-SI-2C HALA

dispensable / 2 parts / Low Volatile Siloxanes (LV) / Form-in-Place

TDG-T-SI-2C is a 2-part dispensable low volatile LV silicone gap filler which is filled with thermally conductive fillers. After curing under heat the system remains elastic. It is characterised by very good dielectric and mechanic properties and is suited for compensating extreme tolerances and spaces at non-coplanar systems. Its thixotropic behaviour allows for a definite placement and cure-in-place. It has a natural low level tack that enhances a good thermal contact. Due to its negligible and controlled volatile content it is suited for environments where volatile silicones and paint wetting impairment are critical.



Release 09 / 2026

PROPERTIES

- ☐ Dispensable 2-part silicone
- ☐ Low volatile siloxane content (LV)
- ☐ No paint wetting impairment
- ☐ Thermal conductivity: 3.0 W/mK
- ☐ Remains elastic after polymerisation
- ☐ Zero stress on components
- ☐ Heat accelerated curing
- ☐ Shock absorbing

AVAILABILITY

- ☐ Cartridges 2 x 25 ml / 2 x 100 ml / 2 x 200 ml / 2 x 600 ml
- ☐ Pail 2 x 25 kg / 2 x 35 kg
- ☐ On request

APPLICATION EXAMPLES

Thermal link of:

- ☐ FPBGA
- ☐ Capacitors
- ☐ Heat Pipes
- ☐ BGA

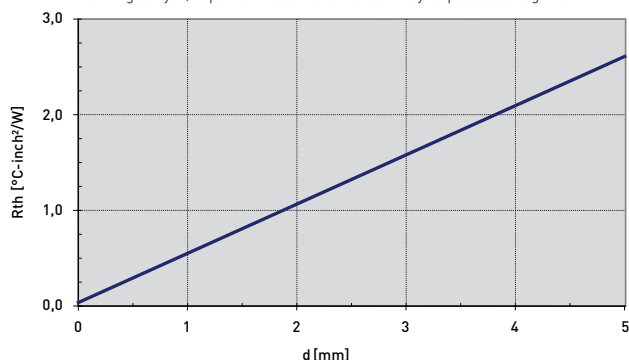
For use in Automotive applications
/ Telecommunication / Multimedia / Industrial PCs

Technical Data Sheet

PROPERTY	UNIT	A Part	B Part
MATERIAL		Silicone	Silicone
Colour		Blue	White
Density @ 25 °C	g/cm ³	2.75	2.75
Mixing Ratio	Weight or Volume	1 : 1	1 : 1
Hardness	Shore 00	55	55
Viscosity (Brookfield @ 10 rpm, 25 °C)	Pas	290	260
Viscosity (mixed) (Brookfield @ 10 rpm, 25 °C)	Pas	275	275
Pot Life @ 25 °C and 65 % RH (Time for viscosity to double)	min	> 120	> 120
Curing Time @ 25 °C / 100 °C		< 15h / 15 - 30 min	< 15h / 15 - 30 min
Shelf Life (from Date of Manufacturing, unopened, @ < 35 °C)	Months	6	6
Outgasing ¹	TML / CVCM / WVR %	0.07 / 0.02 / 0.02	0.07 / 0.02 / 0.02
No Paint Wetting Impairment Substances (PWIS) ²		Passed	Passed
Flammability	UL 94	VO	VO
RoHS Conformity	2015 / 863 / EU	Yes	Yes
TECHNICAL			
Thermal Conductivity ³	W/mK	3.0	3.0
Operating Temperature	°C	- 50 to + 150	- 50 to + 150
Dielectric Strength	kV/mm	> 10	> 10
Volume Resistivity	Ohm - cm	1 x 10 ¹⁰	1 x 10 ¹⁰

Measurement technique according to: ¹ ASTM E 595, ² P-VW 3-10.7 57650 Temp. Test, ³ ASTM D 5470. Typical, non-binding values. Not intended for specification purposes. Subject to technical changes. Please contact us for further information.

Warning: Only A / B part of the same lot number may be processed together.



All technical data and information are without warranty and believed to be reliable and accurate corresponding to the latest state of the art. Since the products are not provided to conform with mutually agreed specifications and their use and processing are unknown we cannot guarantee results, freedom from patent infringement, or their suitability for any application. Product testing by the applicant is recommended. We reserve the right of changes.